MAXIMUM RATINGS

Symbol	Parameter		Value	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0	V	
V _{IN}	DC Input Voltage		-0.5 to +7.0	V
V _{OUT}	DC Output Voltage		-0.5 to $V_{CC}+0.5$	V
I _{IK}	DC Input Diode Current		-50	mA
I _{OK}	DC Output Diode Current		-50	mA
I _{OUT}	DC Output Sink Current		±50	mA
I _{CC}	DC Supply Current per Supply Pin	±100	mA	
T _{STG}	Storage Temperature Range		-65 to +150	°C
ΤL	Lead Temperature, 1 mm from Case for 10 Seconds		260	°C
ТJ	Junction Temperature Under Bias		+ 150	°C
θ_{JA}	Thermal Resistance	SOT-353 (Note 1) SOT-553	350 496	°C/W
PD	Power Dissipation in Still Air at 85°C	SOT-353 SOT-553	186 135	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V–0 @ 0.125 in	
ESD	ESD Classification	Human Body Model (Note 2) Machine Model (Note 3)	4000 400	V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.
Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2-ounce copper trace with no air flow.
Tested to EIA/JESD22-A114-A, rated to EIA/JESD22-A114-B.
Tested to EIA/JESD22-A115-A, rated to EIA/JESD22-A115-A.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter			Max	Unit
V _{CC}	DC Supply Voltage		1.65	5.5	V
V _{IN}	DC Input Voltage		0	5.5	V
V _{OUT}	DC Output Voltage		0	V _{CC} + 0.5	V
T _A	Operating Temperature Range		-55	+125	°C
t _r , t _f	Input Rise and Fall Time $$V_{CC}$= 3$ V_{CC}= 5$ $V_{$.0 V ±0.3 V .0 V ±0.5 V	0 0	100 20	ns/V

			V _{cc}	T _A = 25°C		C	$-55^{\circ}C \leq T_{c}$	_A ≤ 125°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
V _{IH}	High-Level Input Voltage		1.65 to 1.95 2.3 to 5.5	0.75 V _{CC} 0.7 V _{CC}			0.75 V _{CC} 0.7 V _{CC}		V
V _{IL}	Low-Level Input Voltage		1.65 to 1.95 2.3 to 5.5			0.25 V _{CC} 0.3 V _{CC}		0.25 V _{CC} 0.3 V _{CC}	V
V _{OH}	High-Level Output Voltage	I _{OH} = 100 μA	1.65 to 5.5	V _{CC} - 0.1	V _{CC}		V _{CC} - 0.1		V
	$V_{IN} = V_{IL} \text{ or } V_{IH}$	I _{OH} = -3 mA	1.65	1.29	1.52		1.29		
		I _{OH} = -8 mA	2.3	1.9	2.1		1.9		
		I _{OH} = -12 mA	2.7	2.2	2.4		2.2		
		I _{OH} = -16 mA	3.0	2.4	2.7		2.4		
		I _{OH} = -24 mA	3.0	2.3	2.5		2.3		
		I _{OH} = -32 mA	4.5	3.8	4.0		3.8		
V _{OL}	Low-Level Output Voltage	I _{OL} = 100 μA	1.65 to 5.5			0.1		0.1	V
	$V_{IN} = V_{IH} \text{ or } V_{OH}$	I _{OL} = 3 mA	1.65		0.08	0.24		0.24	
		I _{OL} = 8 mA	2.3		0.20	0.3		0.3	
		I _{OL} = 12 mA	2.7		0.22	0.4		0.4	
		I _{OL} = 16 mA	3.0		0.28	0.4		0.4	
		I _{OL} = 24 mA	3.0		0.38	0.55		0.55	
		I _{OL} = 32 mA	4.5		0.42	0.55		0.55	
I _{IN}	Input Leakage Current	$V_{IN} = V_{CC}$ or GND	0 to 5.5			±0.1		±1.0	μA
I _{CC}	Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1		10	μA

DC ELECTRICAL CHARACTERISTICS

AC ELECTRICAL CHARACTERISTICS $t_R = t_F = 3.0 \text{ ns}$

			V _{cc}	T _A = 25°C		$-55^{\circ}C \leq T_{A} \leq 125^{\circ}C$			
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Мах	Unit
t _{PLH}	Propagation Delay	R_L = 1 M Ω , C_L = 15 pF	1.65	2.0	5.5	12.0	2.0	12.7	ns
t _{PHL}	t _{PHL} (Figure 3 and 4)	R_L = 1 M Ω , C_L = 15 pF	1.8	2.0	4.6	10	2.0	10.5	
		$R_L = 1 M\Omega, C_L = 15 pF$	2.5 ± 0.2	0.8	3.0	7	0.8	7.5	
		$R_L = 1 M\Omega, C_L = 15 pF$	3.3 ± 0.3	0.5	2.6	4.7	0.5	5.0	
		$R_L = 500 \ \Omega, \ C_L = 50 \ pF$		1.5	3.0	5.2	1.5	5.5	
		$R_L = 1 M\Omega, C_L = 15 pF$	5.0 ± 0.5	0.5	2.2	4.1	0.5	4.4	
		R_L = 500 Ω , C_L = 50 pF		0.8	2.4	4.5	0.8	4.8	

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	V_{CC} = 5.5 V, V_I = 0 V or V_{CC}	>4	pF
C _{PD}	Power Dissipation Capacitance	10 MHz, V_{CC} = 3.3 V, V_I = 0 V or V_{CC}	25	pF
	(Note 4)	10 MHz, V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	30	

4. CPD is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

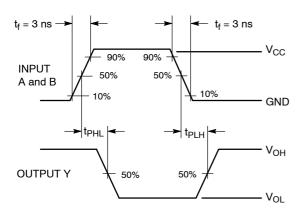
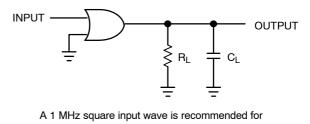


Figure 3. Switching Waveform



propagation delay tests.



ORDERING INFORMATION

Device Order Number	Package Type	Tape and Reel Size [↑]
NL17SZ32DFT2	SC70-5/SC-88A/SOT-353	3000 / Tape & Reel
NL17SZ32DFT2G	SC70–5/SC–88A/SOT–353 (Pb–Free)	3000 / Tape & Reel
NL17SZ32XV5T2	SOT-553*	4000 / Tape & Reel
NL17SZ32XV5T2G	SOT-553*	4000 / Tape & Reel

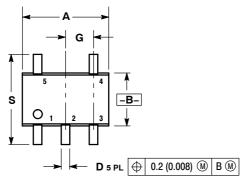
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

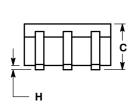
*All Devices in Package SOT553 are Inherently Pb-Free.

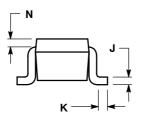
NL17SZ32

PACKAGE DIMENSIONS

SOT-353 (SC-88A, SC-70) **DF SUFFIX** CASE 419A-02 ISSUE J



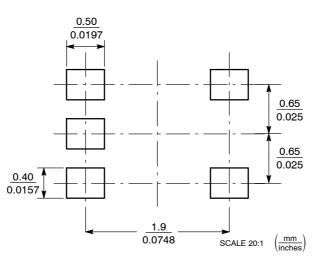




- NOTES:
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: INCH.
 419A-01 OBSOLETE. NEW STANDARD 419A-02.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. BURRS.

	INC	HES	MILLIN	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65	BSC
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
Ν	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20

SOLDERING FOOTPRINT*

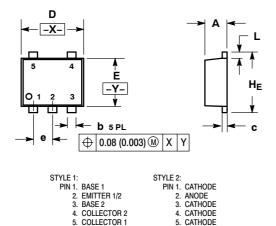


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NL17SZ32

PACKAGE DIMENSIONS

SOT-553 XV5 SUFFIX CASE 463B-01 ISSUE B



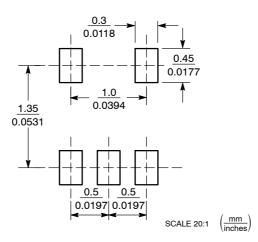
NOTES:

 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETERS

 CONTROLLING DIMENSION: MILLIMETERS
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS				INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.50	0.55	0.60	0.020	0.022	0.024	
b	0.17	0.22	0.27	0.007	0.009	0.011	
С	0.08	0.13	0.18	0.003	0.005	0.007	
D	1.50	1.60	1.70	0.059	0.063	0.067	
E	1.10	1.20	1.30	0.043	0.047	0.051	
е		0.50 BSC		0.020 BSC			
L	0.10	0.20	0.30	0.004	0.008	0.012	
HE	1.50	1.60	1.70	0.059	0.063	0.067	

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and IIIII are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death agsociated with such unintended or unauthorized use payers and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death agsociated with such unintended or unauthorized use poyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81–3–5773–3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative